

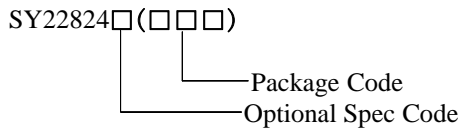
### General Description

The SY22824B is a constant voltage Transition-Mode boost controller with Power Factor Correction (PFC) function. Constant ON Time control is applied to achieve high PF and low THD without multiplier. It drives the Boost converter in the Quasi-Resonant mode for high efficiency and better EMI performance. It adopts special design to achieve quick start up and reliable protection for safety requirement.

### Features

- Valley Turn-on to Achieve Low Switching Losses
- Frequency Reduce in Light Load
- Internal High Current MOSFET Driver: 70Ma Sourcing and 400mA Sinking
- MOSFET Over-Current Protection (OCP)
- Internal THD Optimization to Achieve Low THD
- Internal Transition Optimization
- Compact Package: SOT23-6

### Ordering Information



Ordering Number	Package type	Note
SY22824BABT	SOT23-6	----

### Applications

- AC Adapter Front End
- LED Drivers and Luminaries

### Typical Applications

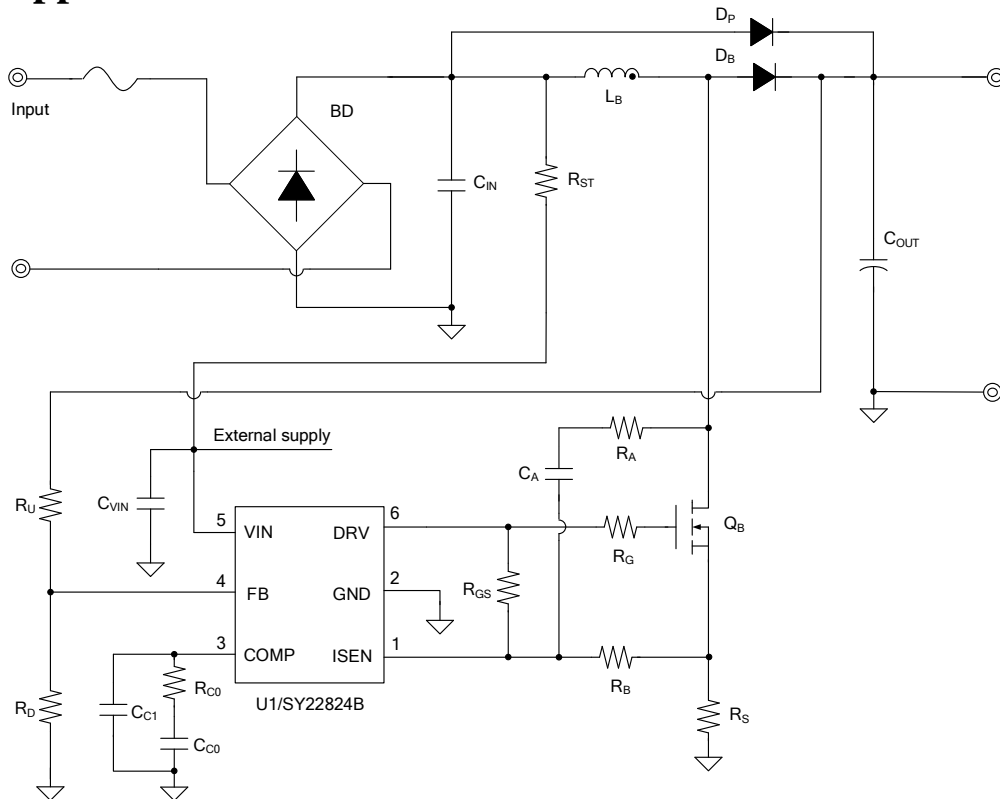
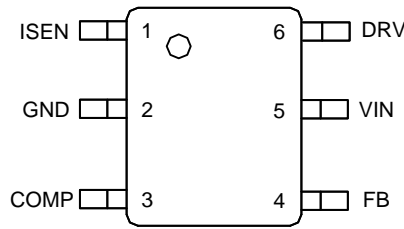


Figure 1. Schematic Diagram

## Pinout (top view)



(SOT23-6)

**Top Mark: d9xyz** (device code: d9, *x=year code, y=week code, z=lot number code*)

Pin	Name	Description
1	ISEN	Current limit and Valley detection pin.
2	GND	Ground pin.
3	COMP	Loop compensation pin. Connect a RC network across this pin and ground to stabilize the control loop.
4	FB	Feedback pin. This pin receives output feedback voltage. The internal reference is 1.25V.
5	VIN	Power supply pin.
6	DRV	Gate driver pin. Connect this pin to the gate of MOSFET with a resistor.

## Block Diagram

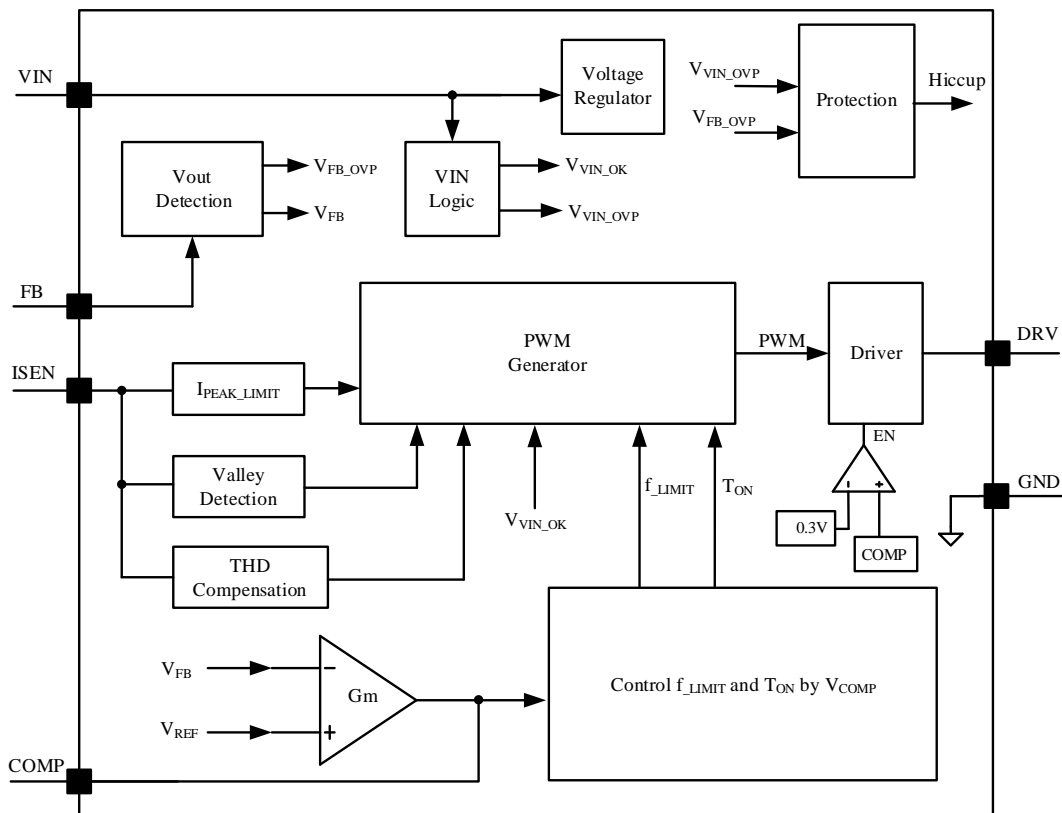


Figure 2. Block Diagram

## Absolute Maximum Ratings (Note 1)

VIN	-----	-0.3V to 28V
DRV	-----	-0.3V to 25V
I <sub>SEN</sub>	-----	-0.3V <sup>(*)</sup> to 25V
COMP, FB	-----	3.6V
Power Dissipation, @ T <sub>A</sub> = 25°C SOT23-6	-----	0.53W
Package Thermal Resistance (Note 2)		
SOT23-6, θ <sub>JA</sub>	-----	234°C/W
SOT23-6, θ <sub>JC</sub>	-----	39°C/W
Temperature Range	-----	-40°C to 150°C
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-65°C to 150°C
(*)Dynamic I <sub>SEN</sub> Negative Current in 50 uS Duration		----- -2mA

## Recommended Operating Conditions (Note 3)

VIN, DRV	-----	9V~22V
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## Electrical Characteristics

(V<sub>IN</sub> = 12V (Note 3), T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Power Supply Section</b>						
VIN Turn-on Threshold	V <sub>VIN_ON</sub>		7.7	8.8	9.8	V
VIN Turn-off Threshold	V <sub>VIN_OFF</sub>		6.6	7.6	8.7	V
VIN OVP Voltage	V <sub>VIN_OVP</sub>		22.0	24.0	26.0	V
Start up Current	I <sub>ST</sub>	V <sub>VIN</sub> < V <sub>VIN_ON</sub>	0.7	1.7	2.7	μA
Quiescent Current	I <sub>Q</sub>	No switching	0.25	0.40	0.55	mA
Discharge Current in Protection Mode	I <sub>VIN_P</sub>	V <sub>VIN</sub> > V <sub>VIN_OVP</sub> (Note 4)		5.0		mA
<b>I<sub>SEN</sub> PIN Section</b>						
Current Limit Voltage	V <sub>I<sub>SEN</sub>_LIMIT</sub>		0.44	0.50	0.55	V
<b>Error Amplifier Section</b>						
V <sub>FB</sub> at Fast Start Up	V <sub>FB_LOW</sub>		1.00	1.08	1.16	V
Internal Reference Voltage	V <sub>REF</sub>		1.232	1.250	1.268	V
High Output Voltage Threshold	V <sub>FB_HIGH</sub>		1.30	1.35	1.40	V
OVP Voltage Threshold	V <sub>FB_OVP</sub>		1.42	1.50	1.58	V
<b>DRV PIN Section</b>						
Gate Driver Voltage	V <sub>Gate</sub>		10.5	12.0	13.5	V
Typical Source Current	I <sub>SOURCE</sub>		55	70	85	mA
Typical Sink Current	I <sub>SINK</sub>		300	400	500	mA
Max ON Time	T <sub>ON_MAX</sub>			23		μs



Min ON Time	$T_{ON\_MIN}$			0.5		$\mu s$
<b>Thermal Section</b>						
Thermal Shutdown Temperature	$T_{SD}$			155		$^{\circ}C$

**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2:**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^{\circ}C$  on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2” x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

**Note 3:** Increase VIN pin voltage gradually higher than  $V_{VIN\_ON}$  voltage then turn to 12V.

**Note 4:** Increase VIN pin voltage gradually higher than  $V_{VIN\_OVP}$  voltage then turn down to 12V.

## Operation

The SY22824B is a constant voltage boost controller with Power Factor Correction (PFC) function designed to drive cost-effective converter to comply with line current harmonic limits.

The SY22824B operates in transition mode suitable for PFC applications. Its COT (constant on time) control scheme enables it to obtain near unity power factor without line voltage sensing network.

To achieve higher efficiency and better EMI performance, SY22824B drives Boost MOSFET in the Quasi-resonant mode, which means to turn on the power MOSFET at voltage valley.

Integrate THD compensation which is adjustable for different application to achieve low THD.

Better line transition and load transition due to internal optimization.

The start-up current of SY22824B is rather small (1.9 $\mu$ A typically) and frequency reduce in light load to reduce the standby power loss further.

The SY22824B integrates suitable Source 75mA/Sink 400mA gate driver for fast switching which is good for EMI improvement and IC power-loss.

The SY22824B provides reliable protections such as Over Voltage Protection (OVP), Over Current Protection (OCP), Over Temperature Protection (OTP), etc.

The SY22824B is available with SOT23-6 package for now.

## Applications Information

### Start up

After AC supply or DC BUS is powered on, the capacitor  $C_{VIN}$  across VIN and GND pin is charged up by BUS voltage through a start-up resistor  $R_{ST}$ . The low startup current consumption ( $=1.7\mu$ A) enables minimized standby power dissipation.

Once  $V_{VIN}$  rises to  $V_{VIN-ON}$ , the internal blocks start to work and  $V_{VIN}$  decreases due to the power consumption of IC till the external supply or the auxiliary winding of Boost inductor can afford  $V_{VIN}$ . SY22824B includes an under-voltage lockout (UVLO) which ensures working till  $V_{VIN}$  decreases to be less than  $V_{VIN-OFF}$ . This

hysteresis ensures sufficient time to wait for the  $V_{IN}$  supplied from the external supply or the auxiliary winding.

The entire start up procedure is divided into two sections as shown in Figure 3, wherein,  $t_{STC}$  is the  $C_{VIN}$  charged up section, and  $t_{STO}$  is the output voltage built-up section. The start-up time  $t_{ST}$  composes of  $t_{STC}$  and  $t_{STO}$ . Usually,  $t_{STO}$  is much smaller than  $t_{STC}$ .

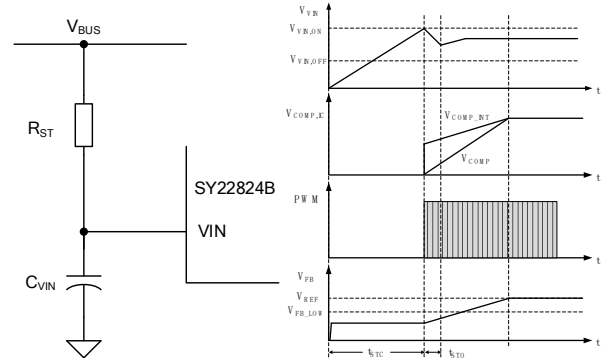


Figure 3. Start up

If  $V_{FB}$  is lower than certain threshold  $V_{FB\_LOW}$ , which means the output voltage is not built up,  $V_{COMP}$  is pulled up by a big resistor ( $R_g$ ) to high clamped  $V_{COMP\_INT}$ ; and hold at this level until  $V_{FB}$  is near to  $V_{REF}$ . This operation is aimed to build up enough output voltage as soon as possible. The simple logical diagram shown as Figure 4.

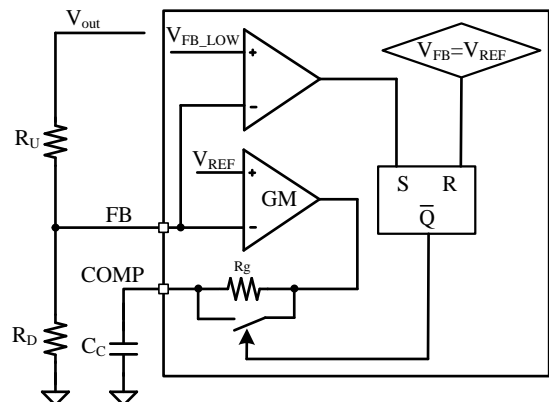


Figure 4. Startup Logical Diagram

If  $R_{ST}$  is connected between rectified BUS line and VIN pin, then the design of  $R_{ST}$  and  $C_{VIN}$  can follow the rules shown below (same as when  $R_{ST}$  is connected between output terminal and VIN pin):

- (a) Preset start-up resistor  $R_{ST}$ , make sure that the current through  $R_{ST}$  is larger than  $I_{ST}$  and smaller than 1mA.

$$\frac{V_{BUS}}{I_{mA}} < R_{ST} < \frac{V_{BUS}}{I_{ST}} \quad (1)$$

Wherein,  $V_{BUS}$  is the BUS line voltage.

(b) Select  $C_{VIN}$  to obtain an ideal start up time  $t_{ST}$  ( $t_{ST} \gg t_{STO}$ ), and ensure the output voltage is built up at one time.

$$C_{VIN} = \frac{\left(\frac{V_{BUS}}{R_{ST}} - I_{ST}\right) \times t_{ST}}{V_{VIN\_ON}} \quad (2)$$

(c) If the energy stored in  $C_{VIN}$  is not enough for IC building up the output voltage smoothly, try to increase  $C_{VIN}$  and decrease  $R_{ST}$ . Then go back to step (a) and redo such design flow till the ideal start up procedure is obtained.

### Shut down

After AC supply or DC BUS is powered off, the energy stored in the BUS capacitor will be discharged. If the auxiliary winding cannot provide enough energy to VIN pin,  $V_{VIN}$  will drop down.

Once  $V_{VIN}$  is lower than  $V_{VIN\_OFF}$ , IC stops working and  $V_{COMP}$  will be discharged to zero.

### Quasi-resonant Operation

QR mode operation provides low turn-on switching losses in MOSFET.

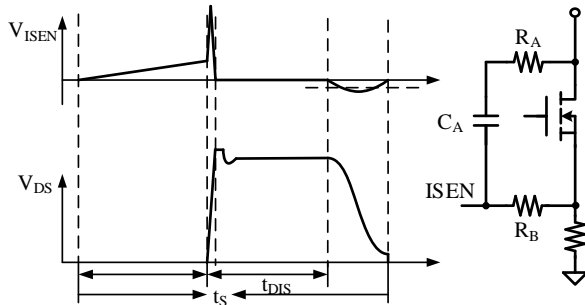


Figure5. QR Mode Operation

The voltage of the MOSFET ( $V_{DS}$ ) is reflected to IC by the RC ( $R_A$ & $C_A$ ) which is connected between the drain of MOSFET and ISEN pin. A resistor ( $R_B$ ) is connected between ISEN pin and ISEN resistor to detect negative voltage for voltage valley.

The capacitor  $C_A$  is need for voltage valley detection. The larger the capacitance capacity, the greater the capacitance loss. Thus,  $C_A=10pF$  and  $R_A=1K$  is recommend.

### Error Amplifier Regulation

SY22824B regulates the boost output voltage using a trans-conductance internal error amplifier (EA). The inverting terminal of the EA is pinned out to FB, the non-inverting terminal is connected to an internal 1.25V voltage reference, and the EA output is pinned out to COMP (Figure 6).

The  $R_k$  is a parasitic resistance that is good for loop control and the resistance is about 8K.

Because of the trans-conductance error amplifier employing, the FB pin can also be used to detect the output over voltage condition and under voltage condition.

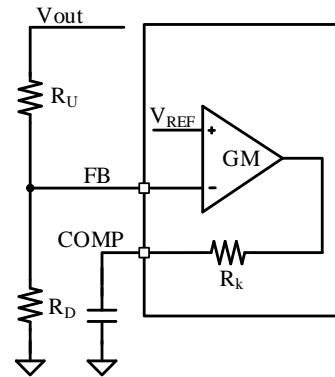


Figure 6. Output Voltage Feedback Circuit

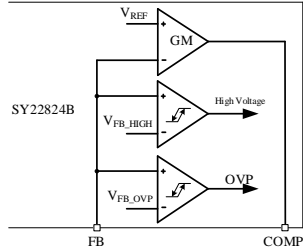
A resistor divider ( $R_U$  and  $R_{DOWN}$ ) scales down the Boost output voltage ( $V_{OUT}$ ) and connects to the FB pin. If the output voltage is less than the regulation, then the control voltage ( $V_{COMP}$ ) increases the on time of the driver, which increases the power transferring from the input to the output. If  $V_{OUT}$  is higher than the regulation, the  $V_{COMP}$  decreases the on time to limit the power transferring.

The output voltage is regulated by equation (3).

$$V_{OUT} = V_{REF} \times \left( \frac{R_U + R_D}{R_D} \right) \quad (3)$$

### Over Voltage Protection (OVP)

Because of the extremely low bandwidth of PFC's voltage loop, there is a risk of overshoots at output side during startup, load steps, and line steps. For reliable operation, the over voltage protection (OVP) is necessary to prevent output voltage from exceeding the ratings of the PFC stage components.



**Figure 7. Output Protection Circuit**

The SY22824B detects the high voltage condition ( $V_{FB\_HIGH}$ ) and stops the DRV of the driver until  $V_{OUT}$  decreases to a safe level, which ensures that  $V_{OUT}$  is within the PFC stage component ratings. In worse conditions, the output voltage continues to rise. When FB is larger than the  $V_{FB\_OVP}$ , the VCC voltage of the chip will be pulled down to UVLO. After the abnormal state of high output voltage is removed, the VCC will restart. Two internal comparator connected to the FB pin provides the output protection.

High output voltage threshold  $V_{FB\_HIGH}$  is 8% above the regulation voltage reference. The high output voltage is calculated using equation (4).

$$V_{OUT} = V_{FB\_HIGH} \times \left( \frac{R_U + R_D}{R_D} \right) \quad (4)$$

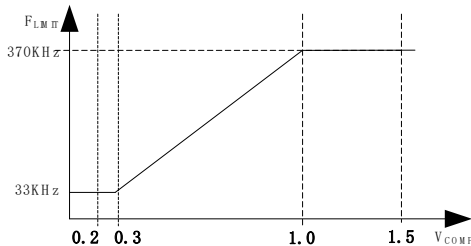
The value of  $C_{bulk}$  is sized to ensure that OVP is not inadvertently triggered by the 100 Hz or 120 Hz ripple of  $V_{OUT}$ .

In the steady states, the minimum value of  $C_{bulk}$  is calculated using equation (5) and assume that the ESR of output capacitor is insignificant.

$$C_{bulk} \geq \frac{P_{OUT}}{2 \times \pi \times V_{ripple(peak-peak)} \times f_{line} \times V_{OUT}} \quad (5)$$

Wherein,  $V_{ripple(peak-peak)}$  is the peak-to-peak output voltage ripple and usually selected in the range of 3.0% of the output voltage;  $f_{line}$  is the ac line frequency (50Hz or 60Hz).

### Frequency reduction & Burst



**Figure 8. Frequency Reduction**

Frequency reduction depends on  $V_{comp}$ :

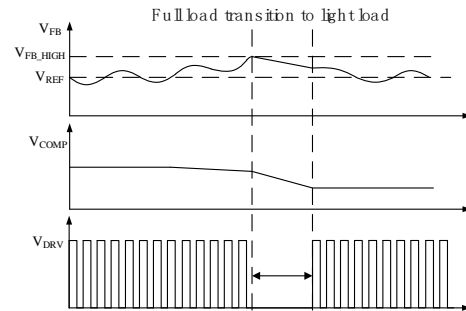
When  $V_{comp} > 1.0V$ , frequency limited at 370 KHz;

When  $V_{comp} < 1.0V$ , frequency will slowly reduce from 400 KHz to 33 KHz.

If the output power continues to decrease, the comp voltage will continue to decrease. When the comp voltage is lower than 300mV, the chip will enter the burst mode.

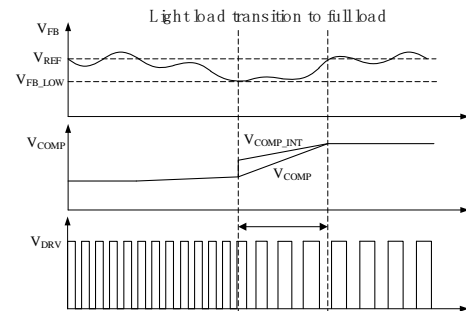
### Special Design for Transition

To have good transition performance, special design is integrate in SY22824B.



**Figure 9. Load Transition (Full load to light load)**

When VSEN touch  $V_{FB\_HIGH}$ , IC will stop DRV to decrease output energy, and then  $V_{COMP}$  decrease by loop to reach a new balance.



**Figure 10. Load Transition (Light load to Full Load)**

When FB touch  $V_{FB\_LOW}$ , a big resistor will be connected to COMP (refer to startup logic), thus,  $V_{COMP\_INT}$  will higher than  $V_{COMP}$ , the ON time of the DRV increase suddenly to expedite output energy until FB reach  $V_{REF}$  and  $V_{COMP}$  equal to  $V_{COMP\_INT}$  again.  $V_{COMP}$  reach a new balance.

Line transition is similar to Load transition. If input

voltage changes from low to high, it can refer to Full load to light load; if input voltage changes from high to light, it can refer to light load to Full load.

### Over Current Protection (OCP)

The dedicated ISEN pin of SY22824B limits the MOSFET peak current cycle by cycle if the voltage of the ISEN pin exceeds  $V_{ISEN\_LIMIT}$ .

The maximum power inductor current ( $I_{PK\_MAX}$ ) occur in minimum input voltage when full load. So  $R_{ISEN}$  could be selected by:

$$R_{sense} = \frac{90\% \times V_{ISEN\_LIMIT}}{I_{PK\_MAX}} \quad (6)$$

Where  $V_{ISEN\_LIMIT}$  is a protection for transformer (If  $V_{ISEN}$  touch this voltage, gate will turn off), and  $I_{PK\_MAX}$  is the maximum inductor current in steady.

### Internal THD Compensation

Because of the existence of the inductance and the capacitance  $C_{ds}$  of the MOSFET, when inductance current is zero, they begin LC resonant. Before the MOSFET switch on, there is a part of negative current in inductance current.

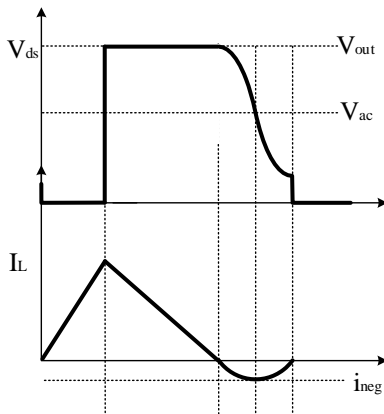


Figure 11. Current of Inductor

The term  $i_{neg}$  is a function of  $V_{ac}$ ,  $V_{out}$ ,  $L$  and  $C_{ds}$ . In fact, during the resonance we can assume no loss and use energy conservation to calculate it:

$$i_{neg} = (V_{out} - V_{ac}) \times \sqrt{C_{ds}/L} \quad (7)$$

From a power frequency period, the waveform of inductor current is shown in Figure 12.

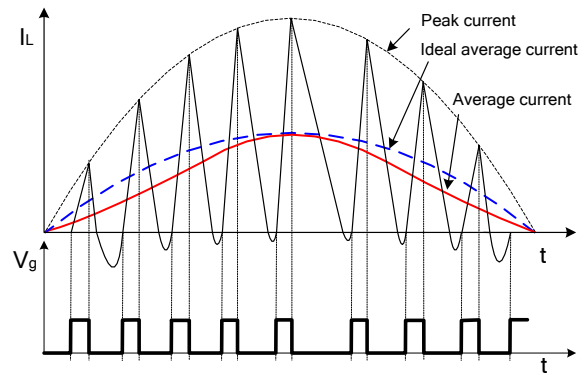


Figure 12. Average Current Waveform of Inductor

Ideal average current which controlled by COT is a sine wave following the input voltage. But the actual average current has been distorted. That is bad for THD performance.

THD compensation helps to remove the effect of negative current to achieve better THD. The analog implementation example shown in Figure 13 is similar to a standard COT with the addition of a voltage comparator with fixed threshold (100mV).

Ton generator does not work until ISEN larger than fixed threshold (100mV). After that, comparator output will be set high to enable the Ton generator and Ton generator begin to work. The compensation current  $\Delta I$  can be calculated using equation (8):

$$\Delta I = 100\text{mV}/R_S \quad (8)$$

If  $\Delta I = i_{neg}$ , the effect of the negative current will be offset and THD will be optimized.

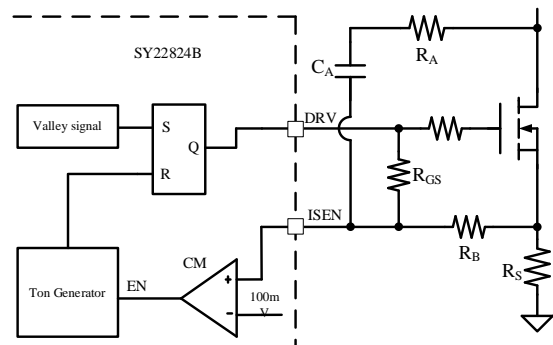


Figure 13. THD Compensation Logic

Actually, different applications will have different LC parameters and  $i_{neg}$  will be difference. The SY22824B support external parameter modification to change the

compensation current and achieve the optimal THD. External parameter is the resistor  $R_B$  and  $R_{GS}$ . Shown in the figure 13.

Assume  $R_{GS} \gg R_B$  and the compensation  $\Delta I$  can be calculated using equation (9).

$$\Delta I = (100mV - \frac{V_{DRV} \times R_B}{R_{GS}}) / R_S \quad (9)$$

Different applications need different  $\Delta I$ .  $R_{GS}$  is the discharge resistor of MOSFET and 10K is recommend. Then changing  $R_B$  can achieve ideal THD performance.

## Power Device Design

### MOSFET and Diode

When the operation condition is maximum voltage input and full load output, the MOSFET and Boost diode suffer the maximum voltage stress.

When the operation condition is minimum voltage input and full load output, the semiconductor devices suffer the maximum current stress.

Maximum input power:

$$P_{in} = \frac{P_{OUT}}{\eta} \quad (10)$$

RMS input current:

$$I_{in} = \frac{P_{in}}{V_{AC\_MIN} \times PF} \quad (11)$$

Peak current of inductor:

$$I_{L(peak)} = 2\sqrt{2} \times I_{in} \quad (12)$$

RMS current of inductor:

$$I_{L(rms)} = \frac{2}{\sqrt{3}} \times I_{in} \quad (13)$$

Peak current of MOSFET:

$$I_{MOSFET(peak)} = I_{DIODE(peak)} = I_{L(peak)} \quad (14)$$

RMS current of MOSFET:

$$I_{MOSFET(rms)} = I_{L(rms)} \times \sqrt{\frac{1}{6} - \left(\frac{4\sqrt{2}}{9\pi} \times \frac{V_{AC\_MIN}}{V_{OUT}}\right)} \quad (15)$$

RMS current of diode:

$$I_{DIODE(rms)} = I_{L(peak)} \times \sqrt{\frac{4\sqrt{2}}{9\pi} \times \frac{V_{AC\_MIN}}{V_{OUT}}} \quad (16)$$

AVE current of diode:

$$I_{DIODE(ave)} = I_{OUT} = \frac{P_{OUT}}{V_{OUT}} \quad (17)$$

Wherein,  $P_{OUT}$  is the output power,  $V_{OUT}$  is the output voltage,  $V_{AC\_MIN}$  is the minimum input AC voltage,  $\eta$  is the estimated efficiency.

### Boost inductor

Once the minimum frequency  $f_{S\_MIN}$  is set, the inductance can be induced. According to transition mode operating principle, boost inductance is calculated using equation (18).

$$L_{MAX} = \frac{V_{AC}^2 \times (V_{OUT} - \sqrt{2} \times V_{AC})}{2 \times f_{S\_MIN} \times P_{IN} \times V_{OUT}} \quad (18)$$

Wherein,  $f_{S\_MIN}$  is the preset minimum switching frequency,  $V_{AC}$  is input RMS voltage,  $P_{IN}$  is the input power,  $V_{OUT}$  is the output voltage.

Once the inductance is induced, we can calculate the winding turns for a specific core. The design rules are shown below:

(a) Select the magnetic core and identify the effective area  $A_e$ ;

(b) Preset the maximum magnetic flux  $\Delta B$  normally within 0.22-0.26T;

(c) Calculate winding turns  $N$  using equation (19);

$$N = \frac{L \times I_{L(peak)}}{A_e \times \Delta B} \quad (19)$$

Depending on the chip ISEN limitations, the formula can be further modified to the following formula:

$$N = \frac{L \times V_{ISEN\_LIMIT}}{A_e \times \Delta B \times R_s} \quad (20)$$

And the  $A_e$  value can choose a larger value, such as 0.33T.

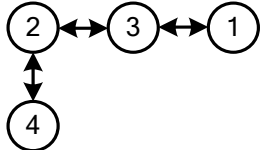
Then select an appropriate wire diameter, grind the core to get required inductance with calculated turns number.

## Layout

(a) To achieve better EMI performance and reduce line frequency ripples, the output of the bridge rectifier should be connected to the BUS line capacitor first, then to the switching circuit.

(b) The circuit loop of all switching circuit should be small: power loop and auxiliary power loop.

(c) The connection of ground is recommended as:



Ground ①: ground of BUS line capacitor

Ground ②: ground of bias supply capacitor

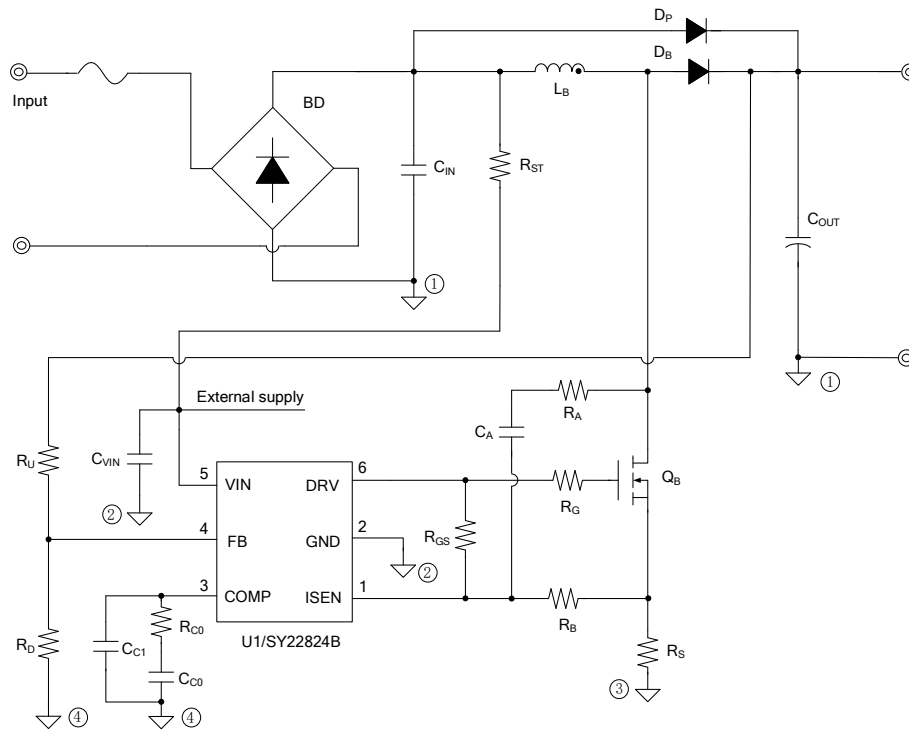
Ground ③: ground node of current sample resistor.

Ground ④: ground of signal trace

(d) Bias supply trace should be connected to the bias supply capacitor first instead of GND pin. The bias supply capacitor should be put near to the IC.

(e) Loop of 'Source pin – current sample resistor – GND pin' should be kept as small as possible.

(f) The resistor divider connected to FB pin is recommended to be put near to the IC.



**Figure 14. Recommended connection of GND**

## Design Example

A design example of typical application is shown below step by step.

### #1. Identify Design Specification

Design Specification			
$V_{AC\_MIN}$	90VAC	$V_{AC\_MAX}$	240VAC
$V_{OUT}$	355V	PF	0.999@ $V_{AC\_MIN}$
$P_{OUT}$	120W	$\eta$	>95%
$f_{s\_min}$	50kHz	$V_{ripple(peak-peak)}$	10V

### #2. Current calculation ( peak and RMS value )

Maximum input power:

$$P_{in} = \frac{P_{OUT}}{\eta} = \frac{120W}{95\%} = 126.3W$$

RMS input current:

$$I_{in} = \frac{P_{in}}{V_{AC\_MIN} \times PF} = \frac{126.3W}{90V \times 0.999} = 1.405A$$

Peak current of inductor:

$$I_{L(peak)} = 2\sqrt{2} \times I_{in} = 2\sqrt{2} \times 1.405A = 3.974A$$

RMS current of inductor:

$$I_{L(rms)} = \frac{2}{\sqrt{3}} \times I_{in} = \frac{2}{\sqrt{3}} \times 1.405A = 1.622A$$

RMS current of MOSFET:

$$I_{MOSFET(rms)} = I_{L(peak)} \times \sqrt{\frac{1}{6} - \left(\frac{4\sqrt{2}}{9\pi} \times \frac{V_{AC\_MIN}}{V_{OUT}}\right)} = 3.974A \times \sqrt{\frac{1}{6} - \left(\frac{4\sqrt{2}}{9\pi} \times \frac{90V}{355V}\right)} = 1.353A$$

RMS current of diode:

$$I_{DIODE(rms)} = I_{L(peak)} \times \sqrt{\frac{4\sqrt{2}}{9\pi} \times \frac{V_{AC\_MIN}}{V_{OUT}}} = 3.974A \times \sqrt{\frac{4\sqrt{2}}{9\pi} \times \frac{90V}{355V}} = 0.895A$$

AVE current of diode:

$$I_{DIODE(ave)} = I_{OUT} = \frac{P_{OUT}}{V_{OUT}} = \frac{120W}{355V} = 0.338A$$

### #3. ISEN resistor

$$R_s = \frac{0.9 \times V_{ISEN\_LIMIT}}{I_{L(peak)}} = \frac{0.9 \times 0.50V}{3.974A} = 0.113\Omega$$

#### #4. Inductor Design ( N and L )

(a)  $f_{s\_min}$  is preset to 50kHz ;

(b) Compute inductor L with minimum and maximum input voltage ;

$$L_1 = \frac{V_{IN}^2 \times (V_{OUT} - \sqrt{2} \times V_{AC})}{2 \times f_{sw\_MIN} \times P_{IN} \times V_{OUT}} = \frac{90V^2 \times (355V - \sqrt{2} \times 90V)}{2 \times 50kHz \times \frac{120W}{0.95} \times 355V} = 41\mu H$$

$$L_1 = \frac{V_{IN}^2 \times (V_{OUT} - \sqrt{2} \times V_{AC})}{2 \times f_{sw\_MIN} \times P_{IN} \times V_{OUT}} = \frac{240V^2 \times (355V - \sqrt{2} \times 240V)}{2 \times 50kHz \times \frac{120W}{0.95} \times 355V} = 200\mu H$$

Choosing 200uH for simply calculation.

(c) core selection;

PQ20/20 (PC40) is selected first.

$$N = \frac{L \times \frac{V_{ISEN\_LIMIT}}{R_s}}{Ae \times \Delta B} = \frac{200\mu H \times \frac{0.50V}{0.113\Omega}}{62mm^2 \times 0.32T} \approx 44$$

(d) wire selection;

According to RMS current calculated before, and current density of 5A/mm<sup>2</sup>, we can get the wire diameter needed.

$$d = \sqrt{\frac{I_{rms}}{5} \times \frac{4}{\pi}} = \sqrt{\frac{1.622A}{5A/mm^2} \times \frac{4}{\pi}} \approx 0.643mm$$

So the diameter of wire for inductor is 0.1mm\*40.

#### #5. Voltage feedback

R<sub>U</sub> is set to 3.1MΩ to reduce resistor loss. Then R<sub>D</sub> is calculated as

$$R_D = \frac{V_{REF} \times R_U}{V_{OUT} - V_{REF}} = \frac{1.25V \times 3.1M\Omega}{355V - 1.25V} = 10.95k\Omega$$

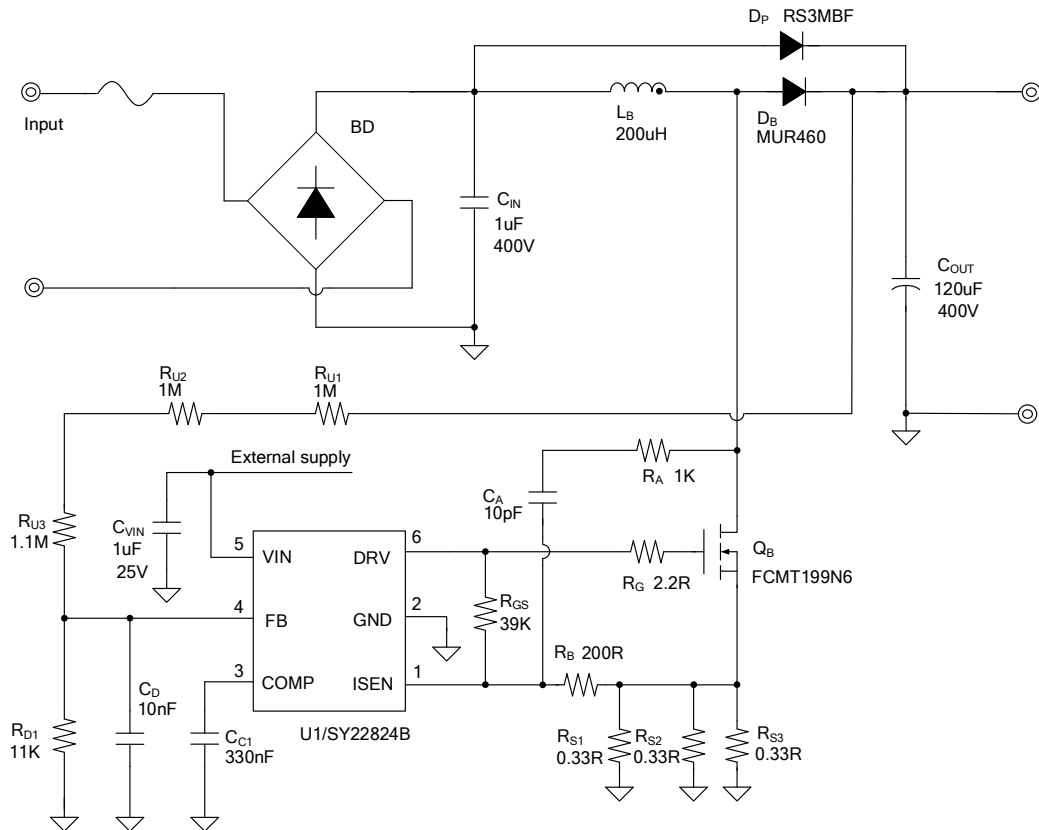
So select R<sub>D</sub> = 11K

#### #6. Output capacitor

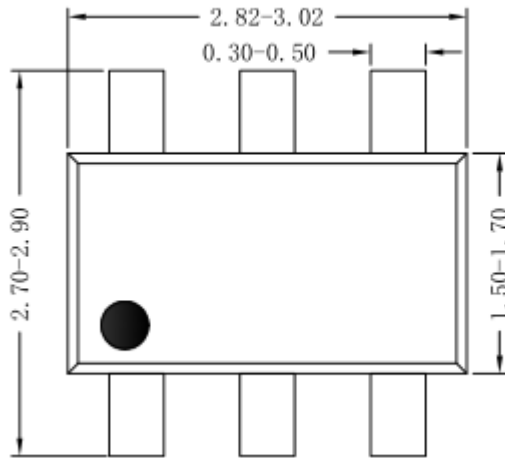
$$C_{bulk} \geq \frac{P_{OUT}}{2 \times \pi \times V_{ripple(peak-peak)} \times f_{line} \times V_{OUT}} = \frac{120W}{2 \times \pi \times 10V \times 50Hz \times 355V} = 107.6\mu F$$

So select C<sub>bulk</sub> = 120uF.

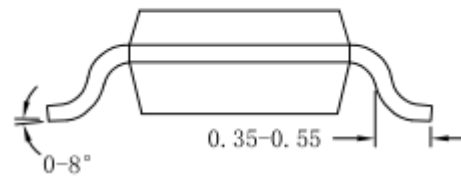
## #7.Recommended Schematic and Parameters



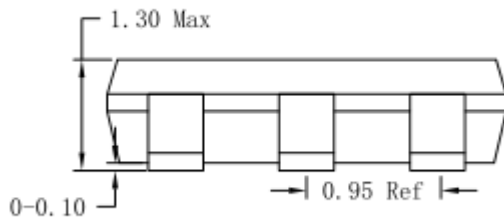
## SOT23-6 Package Outline & PCB layout



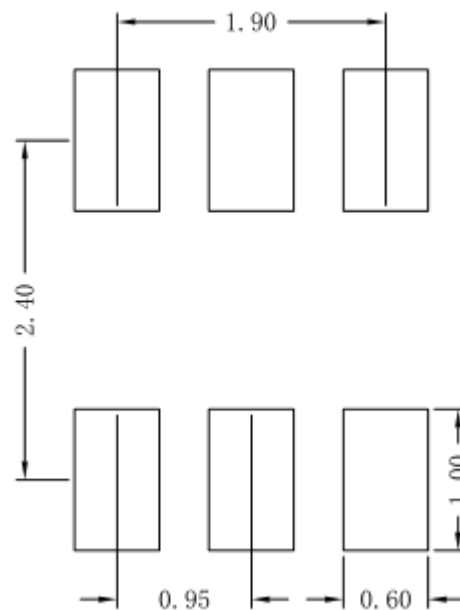
**Top View**



**Side View**



**Side View**



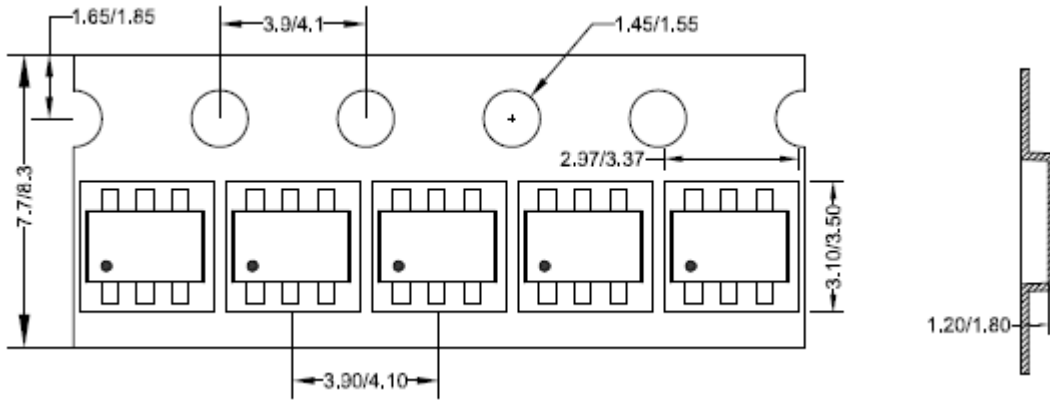
**Recommended Pad Layout**

**Notes: All dimension in millimeter and exclude mold flash & metal burr.**

## Taping & Reel Specification

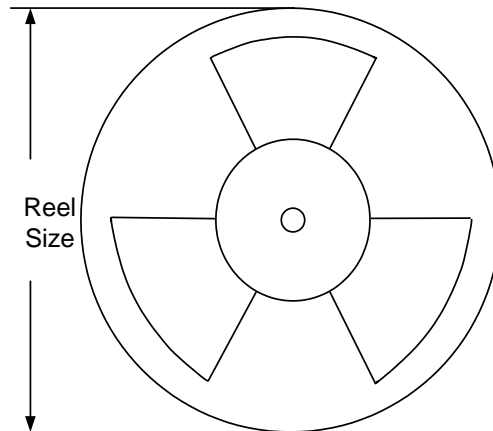
### 1. Taping orientation

SOT23-6



Feeding direction →

### 2. Carrier Tape & Reel specification for packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer * length(mm)	Leader * length (mm)	Qty per reel (pcs)
SOT23-6	8	4	7"	280	160	3000

Others: NA

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## Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

<b>Date</b>	<b>Revision</b>	<b>Change</b>
November 29, 2023	Revision 1.0A	Update the “Applications Information”
October 22, 2021	Revision 0.9	Initial Release

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